



# Wafer Loss Sensor



## Overview

During CMP processing the production wafer should remain captured within the polish head assembly. In the case of a catastrophic failure the wafer or fractured pieces of wafer can slip out from under the polish head. The wafer slip sensor detects this wafer slip and quickly stops all polishing motion. This quick response can prevent additional hardware damage.



## Highlights

- Sensor mounts 8" away from process area, keeping waste from blocking the sensor
- Sensor connects to existing OEM wafer loss PCB
- Sensor Amplifier features a feedback display readout
- A single sensor is used to detect wafer lips on both white and black polish pad simultaneously



# To Find Out More Or To Place An Order See Our Links Below.

To see more part details on the standard wafer loss upgrade click the our video icon.



To email Entrepix parts or to get additional parts information click icon.



To explore, shop and download part information click icon.



To call Entrepix parts dial or click. icon

